# **DSC5002**

# Silicon NPN epitaxial planar type

For general amplification Complementary to DSA5002 DSC2002 in SMini3 type package

#### ■ Features

- High forward current transfer ratio h<sub>FE</sub> with excellent linearity
- ullet Low collector-emitter saturation voltage  $V_{\text{CE(sat)}}$
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

#### ■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

## ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	60	V	
Collector-emitter voltage (Base open)	$V_{CEO}$	50	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V	
Collector current	$I_{C}$	500	mA	
Peak collector current	$I_{CP}$	1	A	
Collector power dissipation	P <sub>C</sub>	150	mW	
Junction temperature	$T_j$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	

### ■ Package

• Code

SMini3-F2-B

- Pin Name
  - 1. Base
  - 2. Emitter
  - 3. Collector

■ Marking Symbol: C2

### ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	$V_{CBO}$	$I_{\rm C} = 10  \mu \text{A},  I_{\rm E} = 0$	60			V
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 2 \text{ mA}, I_{\rm B} = 0$	50			V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu A, I_C = 0$	5			V
Collector-base cutoff current (Emitter open)	$I_{CBO}$	$V_{CB} = 20 \text{ V}, I_{E} = 0$			0.1	μА
Forward current transfer ratio *1	h <sub>FE1</sub> *2	$V_{CE} = 10 \text{ V}, I_{C} = 150 \text{ mA}$	120		340	
	h <sub>FE2</sub>	$V_{CE} = 10 \text{ V}, I_{C} = 500 \text{ mA}$	40			_
Collector-emitter saturation voltage *1	V <sub>CE(sat)</sub>	$I_C = 300 \text{ mA}, I_B = 30 \text{ mA}$		0.1	0.6	V
Transition frequency	$f_T$	$V_{CE} = 10 \text{ V}, I_{C} = 50 \text{ mA}$		160		MHz
Collector output capacitance (Common base, input open circuited)	C <sub>ob</sub>	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		4.8	15	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

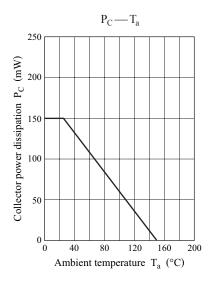
- 2. \*1: Pulse measurement
  - \*2: Rank classification

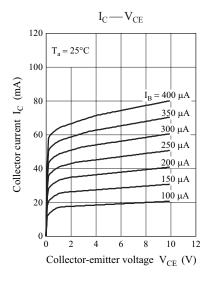
Code	R	S	0	
Rank	R	S	No-rank	
$h_{\mathrm{FE1}}$	120 to 240	170 to 340	120 to 340	
Marking Symbol	C2R	C2S	C2	

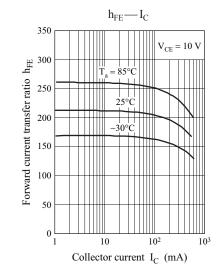
Product of no-rank is not classified and have no marking symbol for rank.

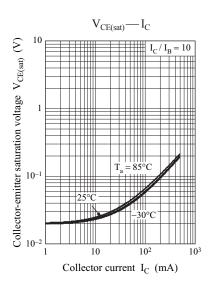
DSC5002

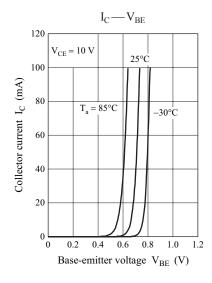
**Panasonic** 

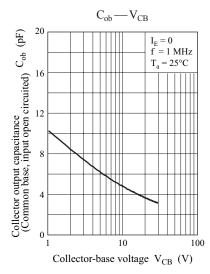


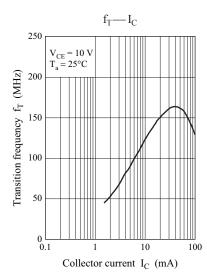








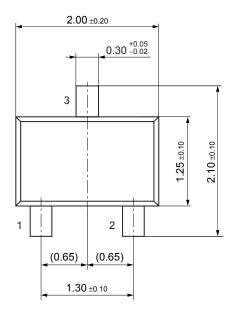


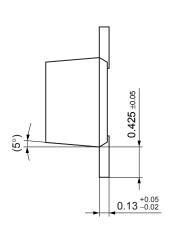


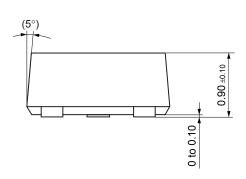
2 Ver. DED

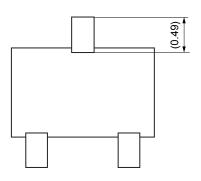
SMini3-F2-B

Unit: mm









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